

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Thomas P. Glenn

Assignee: Amkor Technology, Inc.

Title: Plastic Integrated Circuit Package And Method And Leadframe For Making The Package

Serial No.: 09/615,107

Filing Date:

Examiner: C. Oliva

Group Art Unit: 2831

Docket No.: M-5599-2D US

San Jose, California  
February 20, 2001

COMMISSIONER FOR PATENTS  
Washington, D. C. 20231

RESPONSE TO OFFICE ACTION

Dear Sir:

In response to the Office Action dated December 19, <sup>2000</sup>~~2001~~, please amend the claims as follows. An Information Disclosure Statement is provided herewith.

IN THE SPECIFICATION

At page 4, line 5, replace "position(s)" with --portions--.

At page 5, line 14, insert --of-- between "feature" and "the".

At page 10, line 9, replace "26 and" with --25 and--.

At page 25, line 15, insert --by- between "covered" and "encapsulant".

IN THE CLAIMS

Please cancel all pending claims (nos. 1-4, 7-10, 12, 17, 22-26, 28-30, 32 and 33).

Please add the following new claims.

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